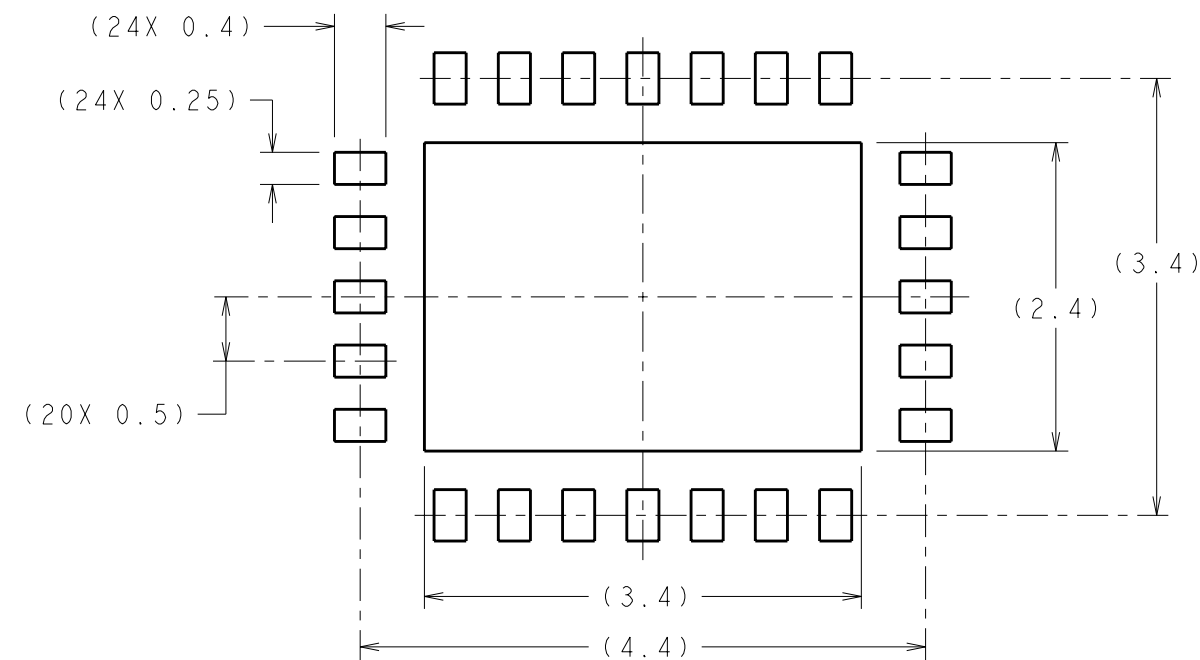
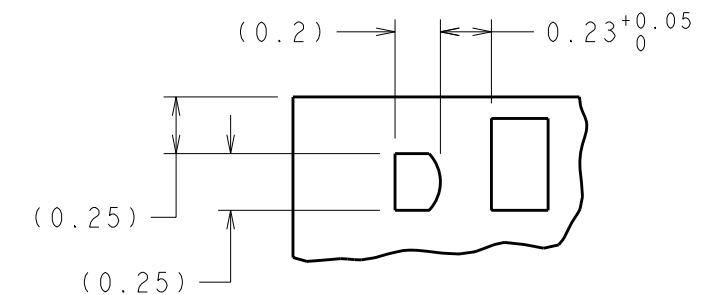


REVISIONS				
REV	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	12436	04/04/2000	SN/TL/JB
B	TITLE: 0.8 WAS 0.75; REVISE NOTES 1 & 2; CHANGE DIM'S IN LAND PATT; ADD DETAIL A; CHANGE DWG FORMAT TO BE SIZE, DIM. (0.1) WAS 0.1 MAX	1237	09/22/2003	TL/RW

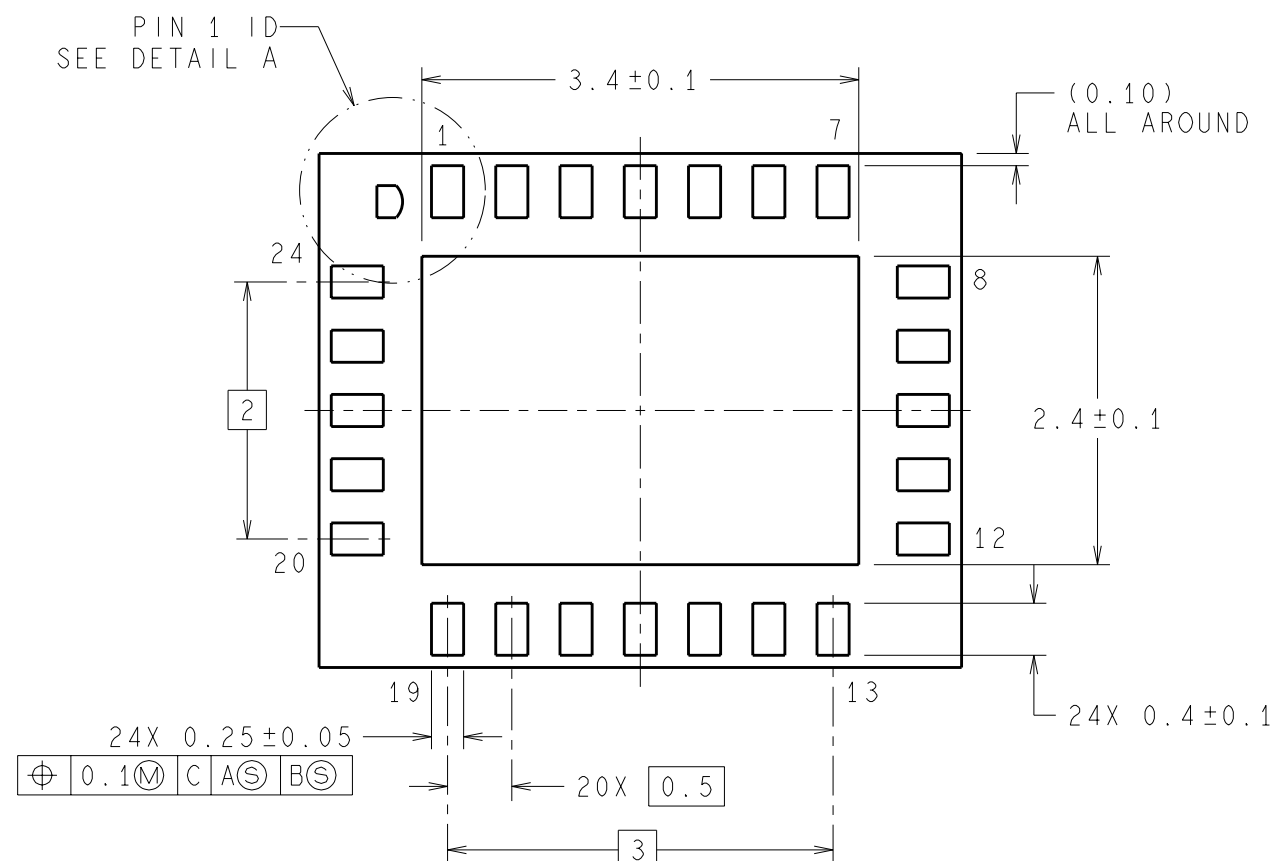
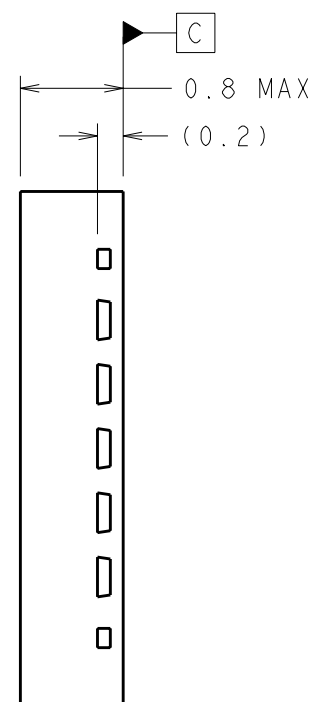
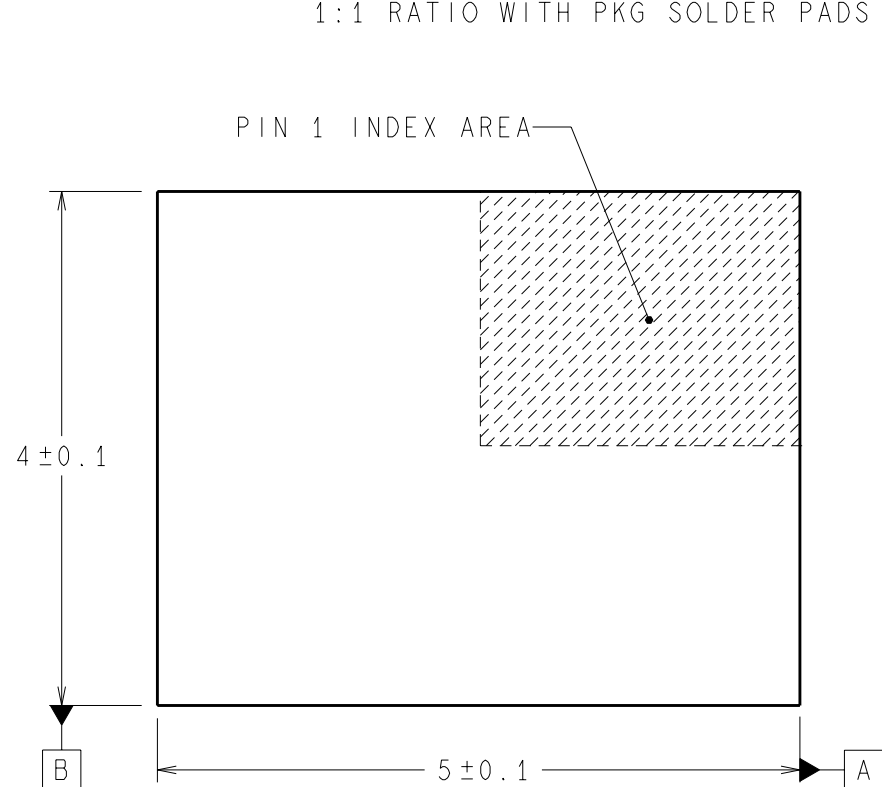


RECOMMENDED LAND PATTERN
1:1 RATIO WITH PKG SOLDER PADS

DIMENSIONS ARE IN MILLIMETERS
DIMENSIONS IN () FOR REFERENCE ONLY



DETAIL A
SCALE: 30X



NOTES: UNLESS OTHERWISE SPECIFIED

- FOR SOLDER THICKNESS AND COMPOSITION, SEE "SOLDER INFORMATION" IN THE PACKAGING SECTION OF THE NATIONAL SEMICONDUCTOR WEB PAGE (www.national.com).
- REFERENCE JEDEC REGISTRATION MO-220, VARIATION WGHD-1.

APPROVALS		DATE	 National Semiconductor 2900 Semiconductor Dr., Santa Clara, CA 95052-8090
DRAWN NSANTHIRAN & TL		04/04/2000	
DFTG. CHK. KURT SINCERBOX		09/22/2003	
ENGR. CHK. RANDALL WALBERG		09/22/2003	
PROJECTION MM			LLP, PLASTIC, QUAD, 5 X 4 X 0.8 mm BODY, 24 LD, 0.5 mm PITCH
SCALE NTS	SIZE B	DRAWING NUMBER (SC)MKT-LQA24A	REV B
FORMERLY: N/A		SHEET 1 of 1	